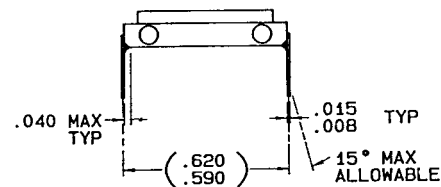
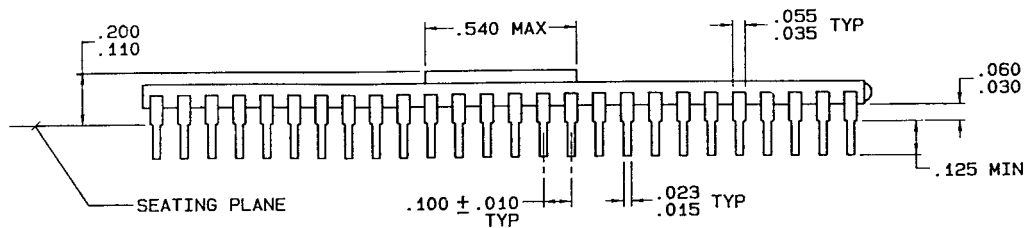
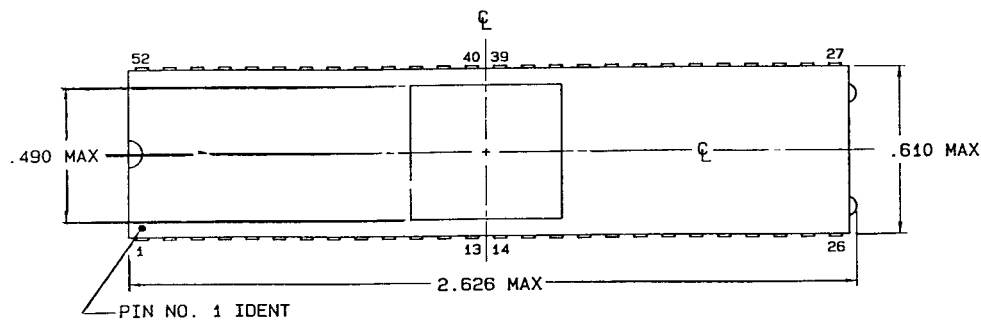


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R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	ORIGINATE	02675	07/29/85	KES/ NAL



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - a) 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - b) 200 TO 800 MICROINCHES TIN PLATE OVER 50 TO 300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
 - c) 50 TO 100 MICROINCHES GOLD OVER 50 TO 350 MICROINCHES NICKEL UNDERPLATE.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE:	APPROVALS	DATE	 NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DECIMALS: .XX ± N/A .XXX ± N/A .XXXX ± N/A	DRAWN KURT SINGER DATE: CHK <i>11/02/85</i> ENGR, 1 CHK <i>11/02/85</i> APPROVAL	07/29/85 08/02/85 08/02/85	HERMETIC DIP (D), SIDE BRAZE, 52 LEAD		
MATERIAL N/A	 PROJECTION 	SCALE N/A	SIZE C	DRAWING NUMBER MKT-D52A	REV A
FINISH N/A		FORMERLY:		SHEET 1 OF 1	
DO NOT SCALE DRAWING					